Session Title:	[TC1] Challenges and Opportunities in CMP
Session Date:	November 21 (Tue.), 2023
Session Time:	08:40-10:10
Session Room:	Room C (Grand Ballroom 2, 2F)
Session Chair:	Prof. Tae Dong Kim (Hannam Univ., Korea)

[TC1-1] 08:40-09:00

Effect of Colloidal Silica and Molybdenum Ions on PVA Brush Loading during Mo Post-CMP Cleaning

Sumit Kumar, Palwasha Jalalzai, Nayoung Kang, Tae-Gon Kim, and Jin-Goo Park (Hanyang Univ., Korea)

[TC1-2] 09:00-09:20

A Better Way of Removing Topography to Improve Surface Roughness of the Tungsten Film

Jongwon Lee, Hyungoo Kong, and Eui-hoon Jung (KCTech, Korea)

[TC1-3] [Invited] 09:20-09:40

Amorphous-Carbon-Layer CMP Mechanism: Dependencies of Polishing-Rate on Film Hardness, Abrasive Material and Abrasive Diameter

Jin-Hyung Park (ENF Tech. Inc., Korea), Seong-In Kim (Hanyang Univ., Korea), Min-Kyu Kim, Sang-Ho Lee (ENF Tech. Inc., Korea), and Jea-Gun Park (Hanyang Univ., Korea)

[TC1-4] [Invited] 09:40-10:10

Challenges and Opportunities in CMP for More Than Moore Innovation

Haedo Jeong (Pusan Nat'l Univ., Korea)